

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JUI HSIEH LAI	09/27/2013
YING-HAO KUO	09/27/2013
KUO-CHUNG YEE	09/27/2013
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14800971
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DATE SIGNED:	07/16/2015
Total Attachments: 1	
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Docket No. T5057-949
TSMC2013-0953

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Jui Hsieh LAI
- 2) Ying-Hao KUO
- 3) Kuo-Chung YEE

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 309, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

APPARATUS AND METHOD FOR CHIP PLACEMENT AND MOLDING

- (a) for which an application for United States Letters Patent was filed on October 23, 2013, and identified by United States Patent Application No. 14/060,764; or
- (b) for which an application for United States Letters Patent was executed on _____.

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) <u>Jui Hsieh LAI</u> Name: Jui Hsieh LAI	<u>2013. 9. 27</u> Date:
2) <u>[Signature]</u> Name: Ying-Hao KUO	<u>2013. 9. 27</u> Date:
3) <u>[Signature]</u> Name: Kuo-Chung YEE	<u>2013. 9. 27</u> Date:

PATENT